

[METHOD OF FABRICATING A SOLDER MASK AND STRUCTURE OF A SUBSTRATE]

Abstract

A substrate includes a dielectric structure, an interconnection structure and a solder mask. The interconnection structure interlaces inside the dielectric structure. The solder mask covers the dielectric structure. The material of the solder mask can be the same as that of the dielectric structure contacting the solder mask. The material of the solder mask can be epoxy resin or bis-maleimide-triazine.